REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	19JAN10	DML
B	GENERAL REVISION	13APR10	DML
C	GENERAL REVISION	13MAR17	DML

6 LAYER STACKUP

NOMINAL FINISHED BOARD THICKNESS 0.062" +/- .007

- PRIMARY SILKSCREEN
- PRIMARY SOLDER MASK
- PRIMARY SIDE
- GND1 PLANE (L2)
- PWR1 PLANE (L3)
- PWR2 PLANE (L4)
- GND2 PLANE (L5)
- SECONDARY SIDE (L6)
- SECONDARY SOLDER MASK
- SECONDARY SILKSCREEN

CHARACTERISTIC IMPEDANCE = 50 OHMS +/- 10%
ARTWORK LINE WIDTH FOR
IMPEDANCE CONTROLLED LINES = 8.5 MILS

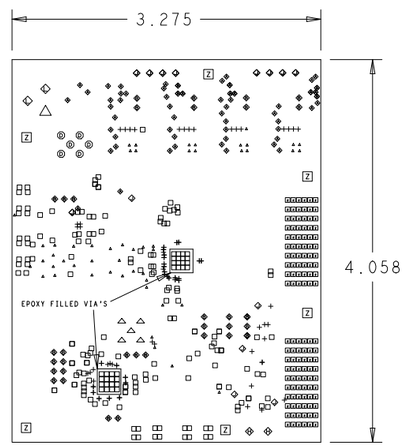
CHARACTERISTIC IMPEDANCE = 100 OHMS DIFF +/- 10%
ARTWORK LINE WIDTH FOR
IMPEDANCE CONTROLLED LINES = 5 MIL TRACE/5 MIL SPACE

NOTES: MATERIALS; MANUFACTURE TO MEET EU RoHS DIRECTIVE, ALL MATERIAL, (INCLUDING SOLDERMASK) REFER TO EU RoHS DIRECTIVE 20002/95/EC.
LAMINATE & RESIN MATERIALS; Tg>170C. Td>310c
ACCEPTABLE MATERIALS; NELCO N4000-11, NELCO N40000-29, ISOLA IS410, POLYCLAD 370 HR, FR4-08.
CLADDING; EXTERNAL LAYERS 1/2 OZ. COPPER, OVERPLATE TO 1 1/2 OZ. INTERNAL SIGNAL LAYERS 1 OZ. COPPER. INTERNAL PLANE LAYERS 1 OZ. COPPER.
SOLDER MASK; SHALL BE LIQUID PHOTOIMAGABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3.
SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR WHITE.
U.L. RATING; 94V0 MINIMUM.
FINISH; SILVER IMMERSION.

FABRICATION:

1. REFER TO IPC-4101B/99 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. UNDIMENSIONED HOLES TO BE LOCATED WITHIN +/-.005 OF THEIR TRUE POSITION WITH RESPECT TO ARTWORK.
3. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
4. HOLE DIAMETERS APPLY AFTER PLATING.
5. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL, INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
6. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
7. MINIMUM DESIGN SPACING IS .008 INCH.
8. BOARD/PANEL MUST MEET IPC-A-600 (LATEST REV.) CLASS 2 FOR FLATNESS.
9. MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
   A. U.L. CODE
   B. DATE CODE (STAMP)
   C. FLAMMABILITY RATING
   D. MFGR. LOGO - DESIGNATED AREA.
   E. SUCCESSFUL ELECTRICAL BOARD TEST.
   F. LOT NUMBER - DESIGNATED AREA.
10. NON-FUNCTIONAL PADS MAY BE REMOVED FROM INNER SIGNAL LAYERS AT MFGR. DISCRETION.
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFGR. MAY TEAR DROP PADS TO MAINTAIN ANNULAR RING AT PAD TO CIRCUIT INTERFACE ONLY AND MUST INSURE ELECTRICAL INTEGRITY.
12. REPAIRS PER IPC-R-700 ARE ALLOWED.
13. MODIFICATIONS TO THE ARTWORK, OTHER THAN THOSE DESCRIBED ON THE FABRICATION DRAWING, ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
14. CORE BETWEEN LAYERS 2 AND 3, AND LAYERS 4 AND 5 SHOULD BE NO MORE THAN 4 MILS IN THICKNESS TO HAVE OPTIMUM INNER PLANE CAPACITANCE.
15. SILKSCREEN CROSS HATCHING UNDER LFCSP PACKAGE (U4) IS REQUIRED AND NOT TO BE REMOVED DURING PROCESSING.
16. VIA'S UNDER U2 & U4 ARE TO BE FILLED WITH NON-CONDUCTIVE EPOXY. THAN PLANERIZED FOR FLATNESS BEFORE FINISH.

FIDUCIALS; TOP & BOTTOM ARE MIRRORED COPIES, (0,200), (0,3800) & (3000,3800)



PRIMARY SIDE

DIMENSIONS ARE FINISHED HOLES SIZE				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	68	
□	12.0	PLATED	180	
▲	16.0	PLATED	51	
◆	20.0	PLATED	58	
⊠	28.0	PLATED	120	
◆	40.0	PLATED	33	
◎	45.0	PLATED	6	
◇	50.0	PLATED	14	
△	63.0	PLATED	5	
◈	65.0	PLATED	2	
◇	120.0	PLATED	2	
△	140.0	PLATED	1	
Z	156.0	NON-PLATED	6	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES
DECIMALS .XX +-.010 .XXX +-.005 FRACTIONS +-1/32 ANGLES +/- 2

MATERIAL

FINISH

DO NOT SCALE DWG

APPROVAL		DATE
DRAWN BY	D.M.L	10/07/07
DESIGNED		
CHECKED		
APPROVED		
MFG ENGINEER		

ANALOG DEVICES
HSC DIVISION
7910 TRIAD CENTER DRIVE
GREENSBORO,NC 27409

TITLE
AD9434 ENG. EVAL.PCB

SIZE	FSCM NO	DRAWING NUMBER	REV
C		09-049125	C

SCALE 1/1 SHEET 1 OF 1